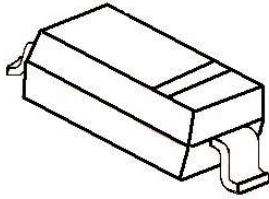


SOD-123 贴片塑封肖特基二极管
SOD-123
SOD-123 Plastic-Encapsulate Schottky Barrier Diode

Marking: SD103AW: S4
SD103BW: S5
SD103CW: S6
特征 Features

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

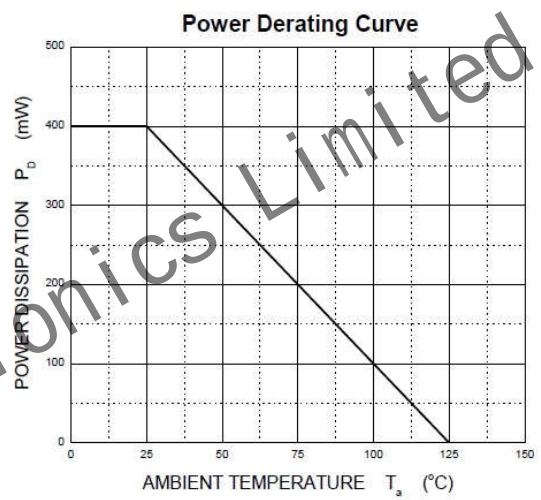
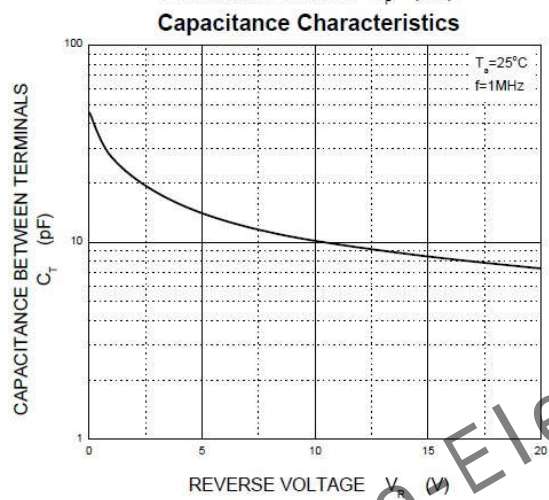
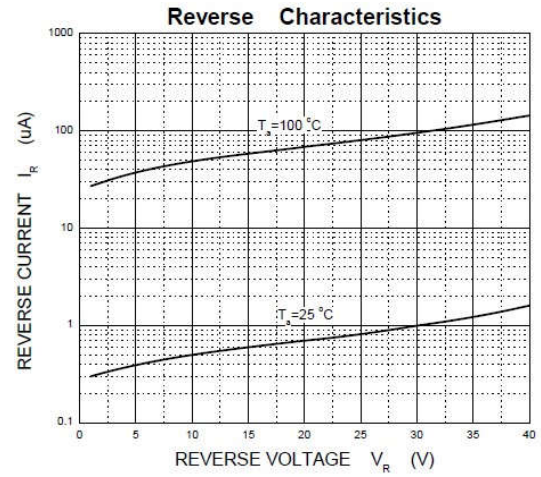
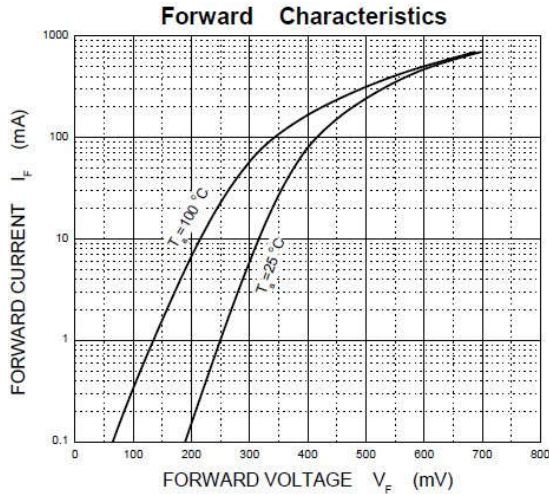
Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	ASB103A EX0	ASB103B EX0	ASB103C EX0	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	VRRM	40	30	20	V
最大均方根电压 Maximum RMS voltage	VRMS	28	21	14	V
最大直流阻断电压 Maximum DC blocking voltage	VDC	40	30	20	V
最大正向平均整流电流 Maximum average forward rectified current	IFM	350			mA
峰值正向浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	IFSM	2			A
功率消耗 Power Dissipation	PD	400			mW
典型热阻 T typical thermal resistance	RθJA	250			℃/W
工作结温 Operating junction temperature	Tj	125			℃
存储温度 Storage temperature range	TSTG	-50-+150			℃

电特性 (TA = 25℃ 除非另有规定)

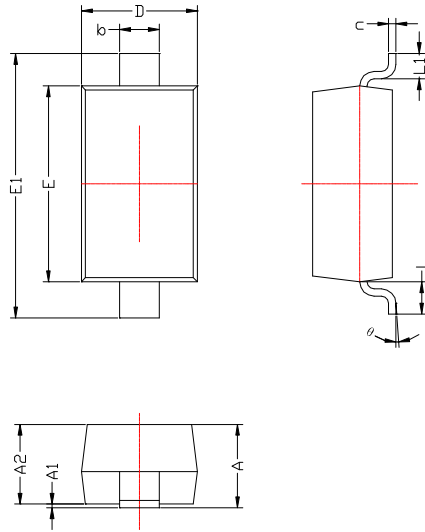
Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified).

参数 Parameters	符号 Symbol	测试条件 Test conditions	ASB103A EX0	ASB103B EX0	ASB103C EX0	单位 Unit
最大正向电压 Maximum forward voltage	VF	IF = 20mA IF = 200mA	0.370 0.600			V
最大反向电压 Maximum reverse breakdown voltage	VR	IR=100uA	40	30	20	V
最大反向电流 Maximum reverse current	IR	VR=30V 103A VR=20V 103B VR=10V 103C	5.0			uA
典型结电容 Type junction capacitance	Cj	VR =0V, f = 1MHz	50			pF
反向恢复时间 Reverse recovery time	Trr	IF=IR=200mA, Irr=0.1xIR, RL=100 Ω	10			ns

特性曲线Characteristic Curves


SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

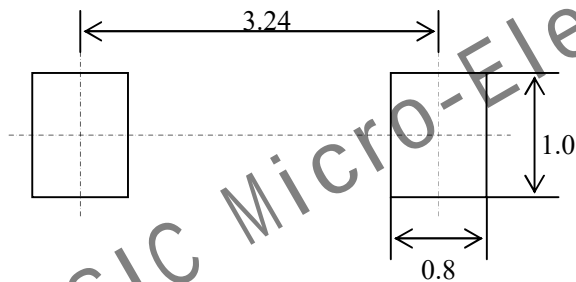


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24
 脚 宽: 0.55
 焊盘宽: 1.00
 脚 长: 0.50
 焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2: 未注公差为: ± 0.05
- 3, 所有单位: mm